

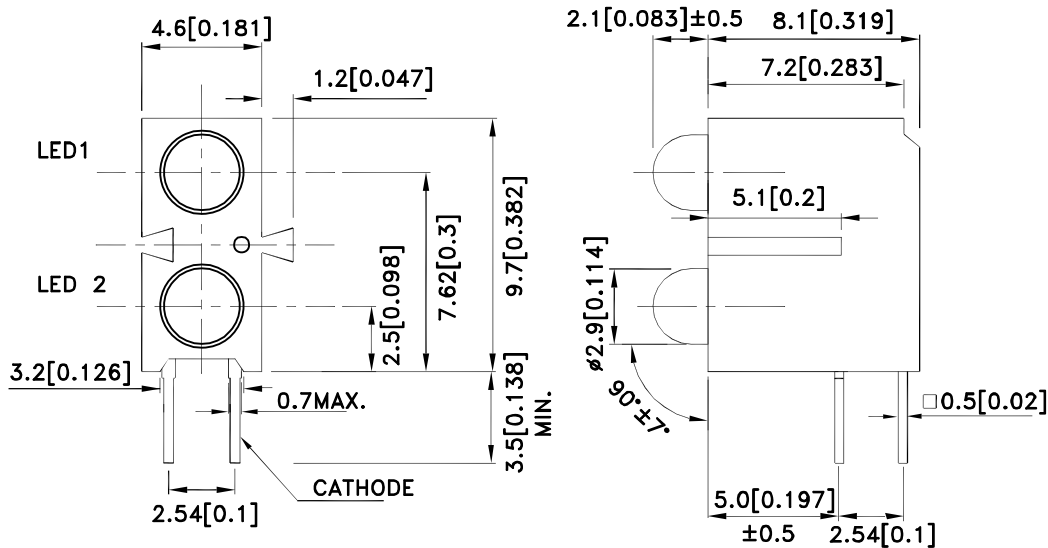
### Features

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating: 94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

### Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP934CA/2YD-90	Yellow (GaAsP/GaP)	Yellow Diffused	8	15	40°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ Luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Yellow	590		nm	I <sub>F</sub> =20mA
λ <sub>D</sub> [1]	Dominant Wavelength	Yellow	588		nm	I <sub>F</sub> =20mA
Δλ <sub>1/2</sub>	Spectral Line Half-width	Yellow	35		nm	I <sub>F</sub> =20mA
C	Capacitance	Yellow	20		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub> [2]	Forward Voltage	Yellow	2.1	2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Yellow		10	uA	V <sub>R</sub> = 5V

Notes:

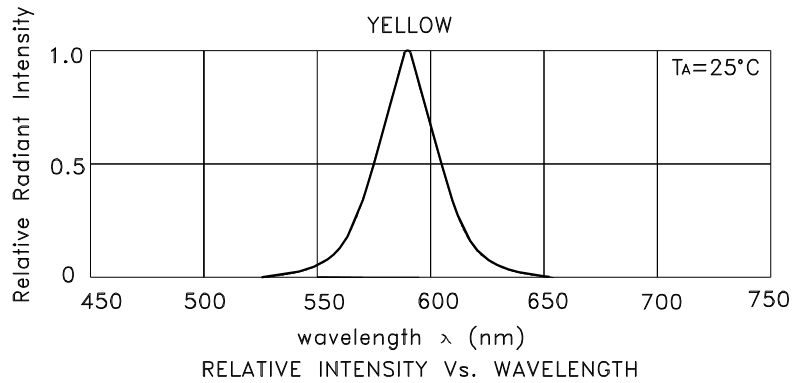
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

## Absolute Maximum Ratings at TA=25°C

Parameter	Yellow	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

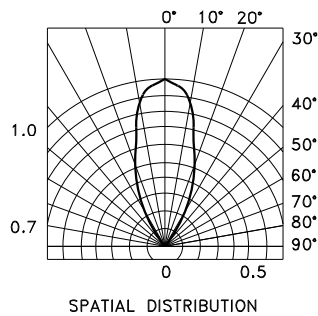
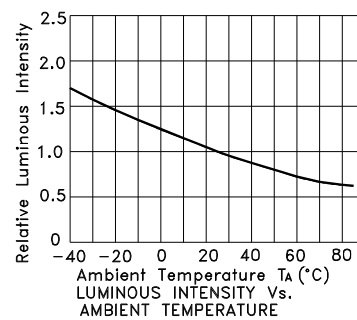
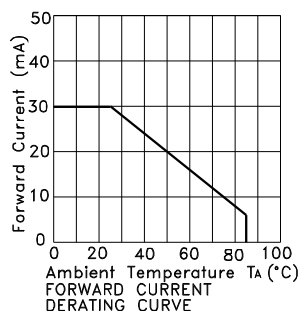
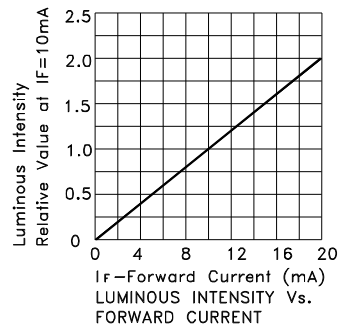
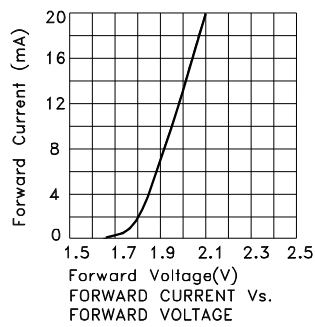
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



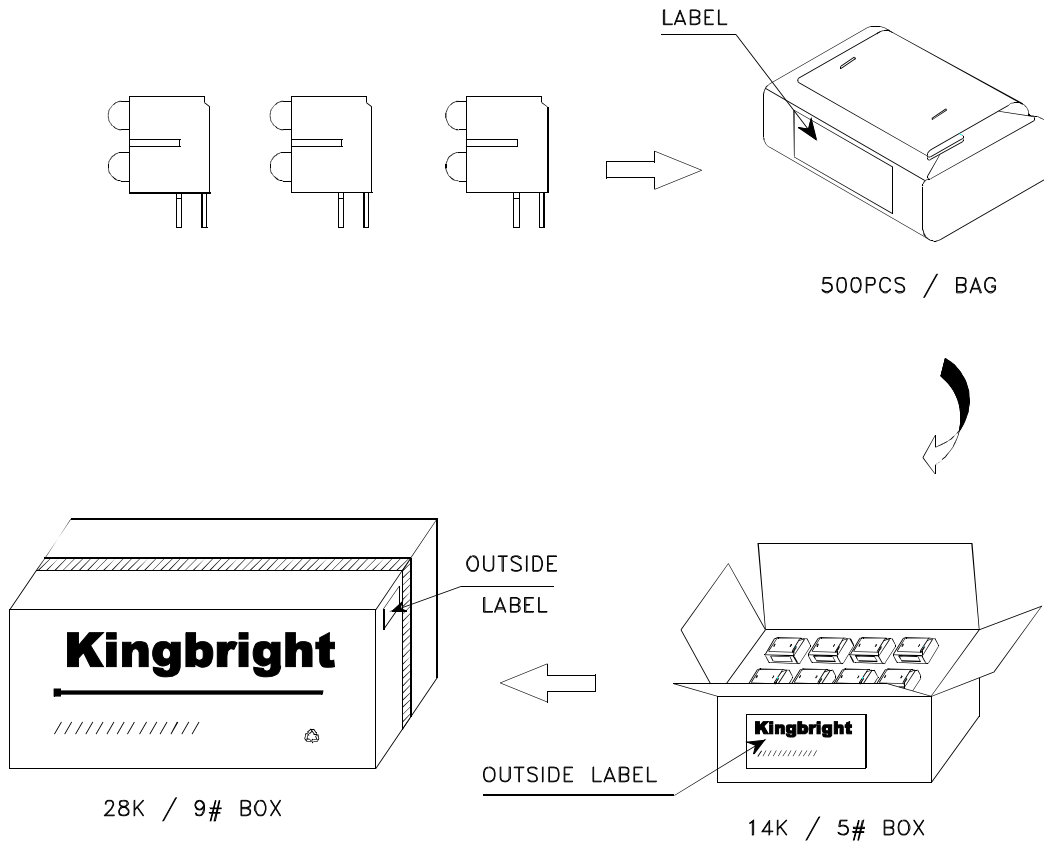
## Yellow

### WP934CA/2YD-90



**PACKING & LABEL SPECIFICATIONS**

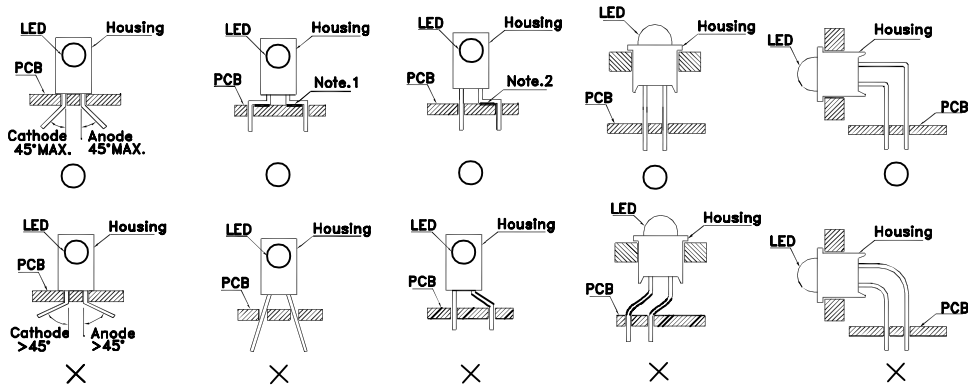
**WP934CA/2YD-90**



<h2 style="margin: 0;">Kingbright</h2>					
P/NO:WP934CAxxx					
QTY: 500 pcs	Q.C.	<table border="1" style="margin: 0 auto;"> <tr><td style="text-align: center;">Q C</td></tr> <tr><td style="text-align: center;">xx xx xxxx</td></tr> <tr><td style="text-align: center;">PASSED</td></tr> </table>	Q C	xx xx xxxx	PASSED
Q C					
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PASSED					
S/N: XXXX					
CODE: XXX					
LOT NO:					
xxxxxxxxxxxxxxxxxxxxxxxx					
RoHS Compliant					

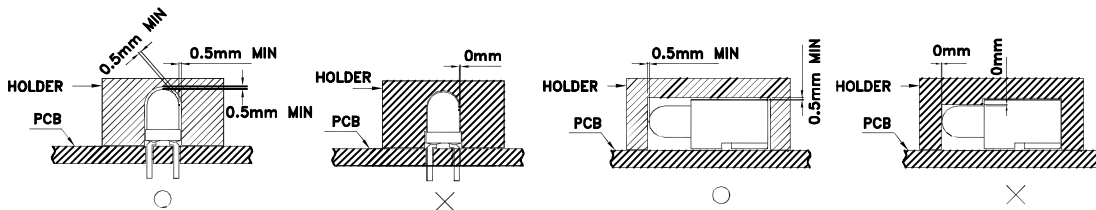
## PRECAUTIONS

- The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

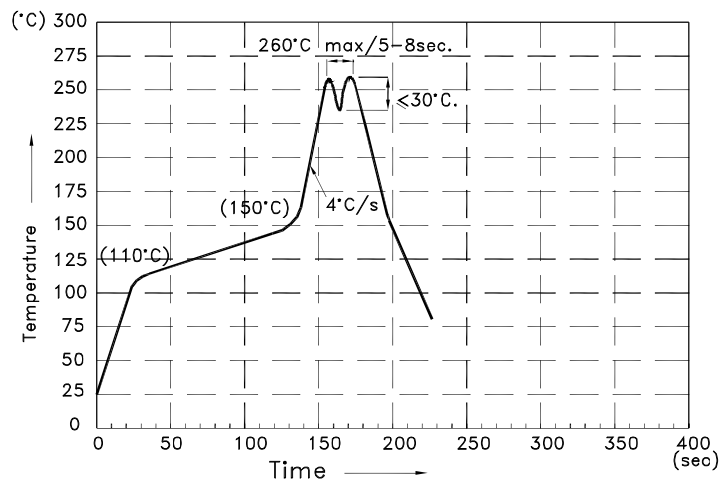


”○” Correct mounting method ”×” Incorrect mounting method

- During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- The tip of the soldering iron should never touch the lens epoxy.
- Through-hole LEDs are incompatible with reflow soldering.
- If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- Recommended Wave Soldering Profile for Kingbright Thru-Hole Products



### NOTES:

- Recommend the wave temperature  $245^{\circ}\text{C}\sim 260^{\circ}\text{C}$ . The maximum soldering temperature should be less than  $260^{\circ}\text{C}$ .
- Do not apply stress on epoxy resins when temperature is over  $85^{\circ}\text{C}$ .
- The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- During wave soldering, the PCB top-surface temperature should be kept below  $105^{\circ}\text{C}$ .
- No more than once.